

IVCR2403/4/5 24V 4A Peak Source and Sink Dual-Channel Driver

1. Features

- Industry standard SOIC-8 pinout
- Two independent gate drive channels
- 4A source and sink peak drive current
- Wide VDD range up to 24V
- Separated enable inputs
- Two channels in parallel for high current driving (IVCR2403/4)
- · Inverting and non-inverting options
- VDD UVLO protection
- TTL and CMOS compatible inputs
- Low propagation delays
- 1ns typical delay matching between two channels (IVCR2403/4)
- Outputs held low when floating inputs
- Operating temperature range -40°C to 125°C

2. Applications

- AC/DC and DC/DC converters
- Server and Telecom rectifiers
- EV/HEV inverters and DC/DC converters
- PV boosters and inverters
- UPS
- Motor Control
- Emerging Wide Band-Gap Power Devices

3. Description

The IVCR2403/4/5 is a 4A dual-channel, high-speed, low-side gate driver, capable of effectively and safely driving MOSFETs and IGBTs. Low propagation delay and mismatch and compact SOIC-8 package enables MOSFETs to switch at hundreds of kHz. It is very suitable for server and telecom power supply's synchronous rectification driving, where synchronous MOSFET's dead time accuracy directly impacts converter's efficiency. The driver is capable to parallel two channels to increase output driving current. The input thresholds are based on TTL with voltage tolerance from -5V to 20V.

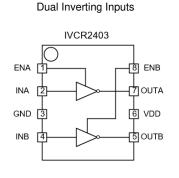
Wide VDD operating range from 4.5V to 20V enables effective driving with MOSFET or GaN power switches. Integrated UVLO protection ensures output held at low under abnormal conditions.

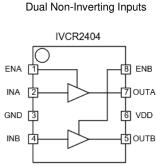
The independent inputs range from -5V to 24V ensure robust operation with undershoot or overshoot induced by parasitic inductances. The input thresholds are compatible with TTL input.

Device Information

PART NUMBER	PACKAGE	PACKING
IVCR2403DR	SOIC-8	Tape and Reel
IVCR2403D	SOIC-8	Tube
IVCR2404DR	SOIC-8	Tape and Reel
IVCR2404D	SOIC-8	Tube
IVCR2405DR	SOIC-8	Tape and Reel
IVCR2405D	SOIC-8	Tube

Pin Configuration





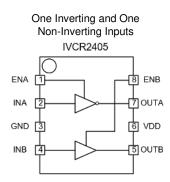




Table of Contents

1	Features	1
2	Applications	1
3	Description	1
4	Pin Configuration and Functions	2
5	Specifications	3
6	Typical Characteristics	5
7	Detailed Description	6
8	Application and Implementation	7
9	Layout	8
10	Packaging Information	9

4. Pin Configuration and Functions

PIN	NAME	I/O	DESCRIPTION
1	ENA		Channel A enable input
2	INA		Channel A input
3	GND	G	Driver ground
4	INB		Channel B input
5	OUTB	0	Channel B driver output
6	VDD	Р	Positive bias supply
7	OUTA	0	Channel A driver output
8	ENB		Channel B enable input

Truth Table

VDD is higher than UVLO threshold. OUTx (x = A or B) is independently controlled by INx and ENx.

IVCR2403/4/5			IVCR	2403	IVCR	2404	IVCR	2405	
ENA	ENB	INA	INB	OUTA	OUTB	OUTA	OUTB	OUTA	OUTB
H or floating	H or floating	L	L	Н	Н	L	L	Н	L
H or floating	H or floating	L	Н	Н	L	L	Н	Н	Н
H or floating	H or floating	Н	L	L	Н	Н	L	L	L
H or floating	H or floating	Н	Н	L	L	Н	Н	L	Н
L	Ш	Χ	Χ	L	L	L	L	L	L
X	X	floating	floating	L	L	L	L	L	Ĺ



5. Specifications

5.1 Absolute Maximum Ratings

Over free-air temperature range (unless otherwise noted) (1)

		MIN	MAX	UNIT
V_{DD}	Total supply voltage (reference to GND)	-0.3	24	V
OUTA, OUTB	Gate driver output voltage	-0.3	V _{DD} +0.3	V
INA, INB	Signal input voltage	-5	24	V
TJ	Junction temperature	-40	150	°C
T _{STG}	Storage temperature	-65	150	°C

⁽¹⁾ Operating beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. Exposure to absolute maximum rated conditions for extended period may affect device reliability.

5.2 ESD Rating

		Value	UNIT
V _(ESD) Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	+/-2000	V
	Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾	+/-500	V

⁽¹⁾ JEDEC document JEP155 states that 500V HBM allows safe manufacturing with a standard ESD control process.

5.3 Recommended Operation Conditions

		MIN	MAX	UNIT
V_{DD}	Supply voltage	4.5	20	V
V _{INx, ENx}	Input voltage	0	20	٧
T _A	Ambient temperature	-40	125	°C

5.4 Thermal Information

		Value	UNIT
Reja	Junction-to-Ambient	128	°C/W
Rejb	Junction-to-PCB	68.5	°C/W

⁽²⁾ JEDEC document JEP157 states that 250V CDM allows safe manufacturing with a standard ESD control process.



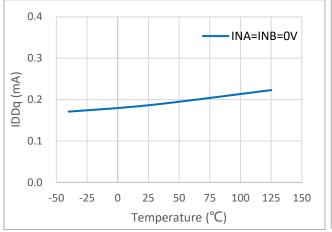
5.5 Electrical Specifications

Unless otherwise noted, $V_{DD} = 12 \text{ V}$, $T_A = -40 ^{\circ}\text{C}$ to $125 ^{\circ}\text{C}$ Currents are positive into and negative out of the specified terminal. Typical condition specifications are at $25 ^{\circ}\text{C}$.

P	ARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
BIAS C	URRENT					
I _{DDoff}	Startup current	VDD=3V, OUTA=OUTB=LOW		70		μΑ
I_{DDq}	Quiescent current	INA=INB=0V		180		μA
	(IVCR2404)	<u> </u>	I			p., ,
Von	Under voltage	Rising threshold		3.8	4.2	
VOFF	thresholds	Falling threshold	3.2	3.5	7.2	V
	(IVCR2403/5)	T dilling timeshold	0.2	0.0		
Von	Under voltage	Rising threshold		3.8	4.25	
VOFF	thresholds	Falling threshold	3.2	3.5	1.20	V
		of IVCR2403 and INA of IVCR2405)	0.2	0.0		
V _{INH}	Input rising					
▼ IIN⊓	threshold			1.8	2.4	V
VINL	Input falling					
• IIVE	threshold		0.8	1.1		V
V _{INHYS}	Input hysteresis			0.8		V
V _{INNS}	Input negative		1_			
- 11410	voltage capability		-5			V
NON-IN		, INB of IVCR2404 and INB of IVCR24	105)			
VINH	Input rising	ĺ	T	0.0	0.4	
	threshold			2.0	2.4	V
VINL	Input falling		0.0	1.0		17
	threshold		8.0	1.2		V
VINHYS	Input hysteresis			0.8		V
VINNS	Input negative		-			V
	voltage capability		-5			V
ENABL	E INPUT (ENA, ENB)		-			
V _{ENH}	Enable input rising			1.8	2.2	V
	threshold			1.0	2.2	>
V_{ENL}	Enable input signal		0.8	1.1		٧
	threshold		0.0	1.1		V
V_{INHYS}	Enable input			0.7		V
	hysteresis			0.7		V
OUTPU	ITS (OUTA, OUTB)					
lo	Peak source and	$C_{LOAD} = 0.22uF,$				
	sink currents	with external current limiting		4		Α
		resistors, 1kHz switching frequency				
VoH	Output high voltage	louтн = -10mA		V_{DD} -0.05 V_{D}		V
Vol	Output low voltage	Ioutl = 10mA		0.0057	0.012	V
Rон	Output static pull-up			5	12	Ω
	resistance					
Rol	Output pull-down			0.57	1.2	Ω
	resistance					
Timing		10.5				
TD _r	Output rising delay	C _{LOAD} = 1.8nF		16		ns
TD _f	Output falling delay	0 105		16		
Tr	Rise time	C _{LOAD} = 1.8nF		6		ns
T _f	Fall time	INIA INID ENIA ENID VOD		6		
T_{dm}	Delay mismatch	INA=INB, ENA=ENB=VDD		1		ns
		(IVCR2403 and IVCR2404)				



6. Typical Characteristics



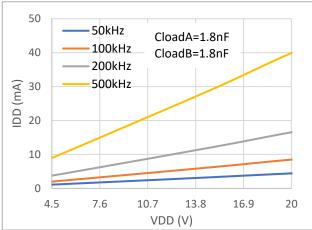
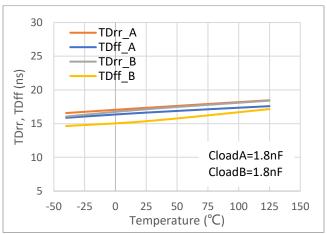


Figure 1. Quiescent Current IDDq vs Temperature

Figure 2. Operating Current IDD vs VDD



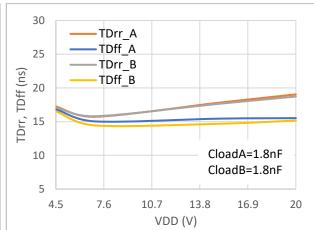
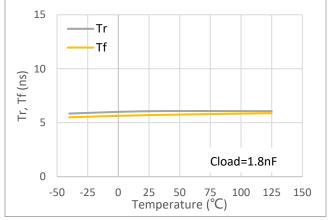


Figure 3. Propagation Delay vs Temperature

Figure 4. Propagation Delay vs VDD



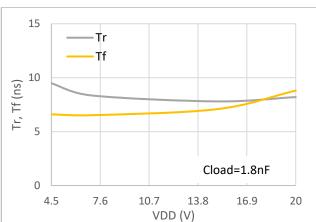


Figure 5. Rise Time and Fall time vs Temperature

Figure 6. Rise Time and Fall time vs VDD



7. Detail Descriptions

IVCR2403/4/5 driver provides dual-channel high-speed low-side gate drive. IVCR2403/4 features tight mismatching outputs when two channels are paralleled to drive large or paralleled power switches.

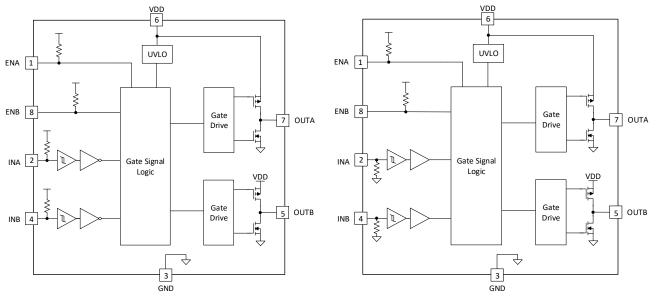


Figure 7. IVCR2403 Block Diagram

Figure 8. IVCR2404 Block Diagram

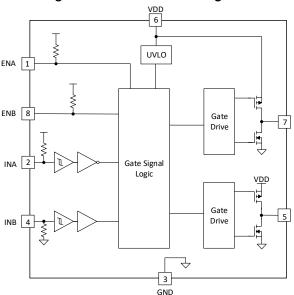


Figure 9. IVCR2405 Block Diagram

7.1 Input Signals INA and INB

INA and INB are gate driver inputs. The pin has a pullup resistor on all the inverting inputs (INA, INB of IVCR2403 and INA of IVCR2405) and has a pulldown resistor on all the non-inverting inputs (INA, INB of IVCR2404 and INB of IVCR2405). When left floating, outputs are pulled to GND. The input is a TTL and CMOS compatible logic level with maximum 24V input tolerance.

7.2 Enable Signals ENA and ENB



ENA and ENB are enable control signals. The enable control signal is a TTL and CMOS compatible logic level with maximum 24V tolerance. When ENx is driven low the OUTx is pulled to GND. When ENx is driven high or left floating, the OUTx follows INx (INA, INB of IVCR2404 and INB of IVCR2405) or is the inverting of INx (INA, INB of IVCR2403 and INA of IVCR2405). The enable pins have a weak pullup.

7.3 OUTA and OUTB

OUTA and OUTB are totem-pole outputs, which consist of a hybrid pullup and an N-channel MOSFET for pulldown. Each output stage in IVCR2403/4/5 can supply 4A peak source and 4A peak sink current pulses. The output voltage swings between VDD and GND providing rail-to-rail operation. The presence of the MOSFET body diodes also offer voltage clamping paths to limit overshoot and undershoot. That means that in many cases, external Schottky diode clamps may not be necessary.

7.4 VDD and Under Voltage Protection

IVCR2403/4/5 maximum voltage rating is 24V. It is suitable for Si MOSFET, IGBT and SiC MOSFET gate drive. The driver has internal under voltage lockout (UVLO) protection feature. When VDD level is below UVLO threshold, this circuit holds the output LOW, regardless of the status of the inputs.

8. Application Implementation

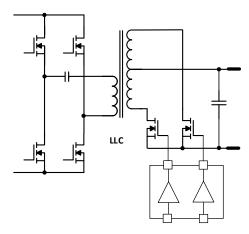


Figure 10. Two channels driven separately (IVCR2403/4/5)

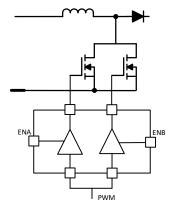


Figure 11. Two paralleled switches driver by two outputs with minimized mismatch (IVCR2403/4)



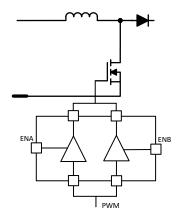


Figure 12. A large switch driver by two paralleled outputs with minimized mismatch (IVCR2403/4)

9. Layout

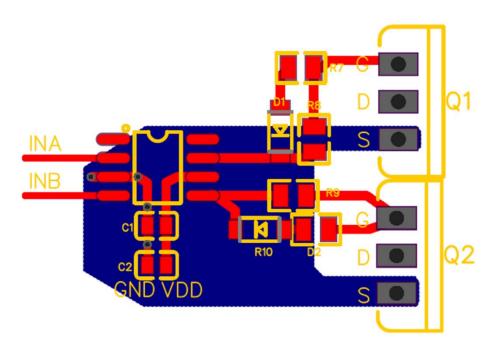
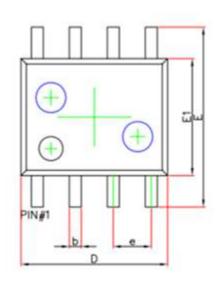


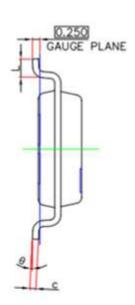
Figure 13. Layout Example for IVCR2403/4/5

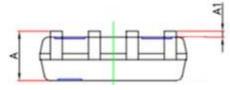


10. Package Information

SOIC-8 Package Dimensions

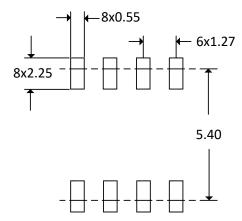






Cymabal	Dimensions in Millimeters		Dimensions in Inches		
Symbol	Min.	Max.	Min.	Max.	
А	1.350	1.750	0.053	0.069	
A1	0.110	0.250	0.004	0.010	
b	0.310	0.510	0.012	0.020	
С	0.130	0.250	0.005	0.010	
D	4.810	5.000	0.189	0.197	
E	5.800	6.190	0.228	0.244	
E1	3.810	3.980	0.150	0.157	
е	1.270		0.0	50	
L	0.410	1.270	0.016	0.050	
θ	0.000	8.000	0.000	0.315	





SOIC-8 Recommended Soldering Dimensions